

This silver paste (low silver content) is formulated for screen printing application on float glass, for **fine line** printing specially (<0.4 mm width, depending on printing conditions and combined with Ag 380x members). The paste is based on low particle size powders allowing a higher conductivity and producing a more dense and sintered fired film. The product is especially recommended when very high chemical resistance is necessary. It also prevents marks caused by the soldering of circuit connectors.

## PROCESSING CONDITIONS

**Printing:** typical industrial parameters 200 – 250 mesh stainless steel screen, or 77 - 90 wires polyester screen.

**Soldering:** 47% Sn, 40% Pb, 10% Bi, 3% Ag solder at 230°C (best conditions).

**Shelf life:** 8 months @ 4°C-10°C, 6 months @ 10-24°C

**Thinners:** Thinning is not recommended, the paste is optimized to the correct viscosity for screen printing. Use the Chimet 0203IT to replace solvent losses (% higher than 0.1% could affect conductivity).

## TYPICAL PROPERTIES

### **Metal content:**

Ag **65.0 %**

### **Sheet Resistance:**

4 µm fired film thickness **6.5 mΩ/□**

### **Resistivity:**

**2.6 µΩ · cm**

### **Viscosity:**

**46 – 60 Pa.s**

## STANDARD TEST CONDITIONS

### **Viscosity test:**

Viscosimeter Brookfield DV II, Cylinder  $\varnothing = 4$  cm h = 7 cm, Spindle 7 R at 10 r.p.m. and 23.5 ( $\pm 0.5$ )°C.

### **Resistance test:**

Circuit:	1000 x 1 mm
Printing :	250 mesh
Drying :	120°C, 10 minutes
Firing:	flash firing @ 740°C, 4 minutes
Fired thickness:	Taylor-Hobson profilometer

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